## LEOCO CORPORATION PRODUCTION SPECIFICATION S-96-7500-3 No.

## 7500 Series And 7501,7502,7506,7507 Series Connector

This product specification contains the test method, the general performance and requirements for interconntection system connector. With 7500 series socket ,7501,7502,7506,7507 series header and 3973,3978,3979,3983 series crimp terminal.

**TEST METHOD & CONDITION** 

测试方法与条件

It should be tested in accordance with

1. Construction and dimensions shall be in accordance with the referenced drawings.

产品结构和尺寸依据所提供的产品图面.

2. Characteristics 特性;

Contact

ITEM

Current rating 额定电流: 7 A AC, DC Voltage rating 额定电压: 250 v AC,DC Temperature rating 额定温度:-25°C----+105°C

Applicable wire 适用线材: conductor construction size # 18----# 26.

3. Electrical performance 电气特性: **DESCRIPTION** 

内容

3.1	Resistance 接触阻抗	method 3004.1 of MIL-STD-1344A	After environmental test: 40 mΩ max					
3.2	Insulation Resistance 绝缘阻抗	It should be tested in accordance with method 3003.1 of MIL-STD-1344A	Initial: 1000 mΩ min After humidity test: 500 mΩ min					
3.3	Dielectric withstanding voltage 耐电压	Unmated connector shall be tested in accordance with method 3001.1 of MIL-STD-1344A When the AC 1500 V rms for one minute applied between adjacent contacts.	No evidence of breakdown and flashover					
4. Mechanical Performance 机械特性:								
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件	REQUIREMENT 需 求					
4.1	Crimp tensile strength 铆合张力强度	Pulling load shall be applied between correctly crimped contact and wire at a constant speed .pulling speed :25 mm/minute.	AWG #18: 10.0 kgf min. AWG #20: 8.0 kgf min. AWG #22: 6.3 kgf min. AWG #24: 4.5 kgf min. AWG #26: 2.7 kgf min.					
4.2	Contact insertion force 接触插入力	The force required to insert a contact into a housing :inserting speed:25 mm/minute.	1.25 kgf max.					
4.3	Contact removal force 接触拨出力	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm/minute.	2.0 kgf min.					
4.4	Insertion force 插入力	Housing with contact mating header at a constant speed of 25 mm/min.	2.0 kgf max					
4.5	Withdrawal force 拔出力	Housing with contact mating header ,pull out from header at speed 25 mm/min.	500 gram min					

SHEET: 1/2

REQUIREMENT

求

需

Initial: 20 mΩ max

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4.6	Durability 耐久性	It should be tested in accordance with method 2016 of MIL-STD-1344A. connectors shall be subjected to 100 cycles of insertion and withdrawal.	C	No defects. Contact resistance shall be 20 MΩ max				
47	Post retention force 保持力	The end of a post shall be pushed in a perpendicular to base housing at a constant speed of 25 mm/minute.	2	2.0 kgf min				
Vibration 4.8 Vibration 振动测试 te		The socket mated header shall be vibrated in accordance with method 2005.1 of MIL-STD-1344A test conditio B.There shall be no current discontinuit longer than 1 microsecond during the test.  Frequency: 10-55-10 hz/min.  Amplitude: 1.52mm  Period: 2 hours for each direction.	n c	No evidence of loosening of parts or electric discontinuity . Contact resistance initial.				
5. Environmental Performance 环境特性:								
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件		REQUIREMENT 需 求				
5.1	Humidity 耐湿性	The unmated connector shall be tested accordance with method 1002.2 of MIL-STD-1344A test procedure type I condition B. Temperature: 40±2°C Humidity:90—95% (RH) Period: 96 hours	in	Conta Less Insula pass Diele	amage. act resistance than twice of initial. ation resistance: to para.3-2. ctric withstanding ge: to pass para 3-3			
5.2	Salt spray 盐雾试验	Connector shall be tested in accordanc with method 1001.1 of MIL-STD-1344A condition B.  Temperature: 35±2°C  Density: 5% in weight.  Period: 48 hours.		No damage. Contact resistance less than twice of initial.				
5.3	Solder ability 着锡性	Connector termination ends shall be checked for solderability in accordance with method 208 of MIL-STD-202F. Solder temperature: 245±5°C Immersion period:5±0.5 sec.		No damage. Minimum: 95% of immersed area.				
5.4	Resistance to soldering heat 附着耐热性	Specimen shall be mounted on PCB. Solder temperature : $260\pm5^{\circ}$ C Immersion period :5 $\pm0.5$ sec.			amage and mation			
APPR I	BY:	CHKD BY :	SPE	PEC BY :				